

SN54AHCT125, SN74AHCT125 QUADRUPLE BUS BUFFER GATES WITH 3-STATE OUTPUTS

SCLS264L – DECEMBER 1995 – REVISED JANUARY 2000

- **EPIC™ (Enhanced-Performance Implanted CMOS) Process**
- **Inputs Are TTL-Voltage Compatible**
- **Latch-Up Performance Exceeds 250 mA Per JESD 17**
- **ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015**
- **Package Options Include Plastic Small-Outline (D), Shrink Small-Outline (DB), Thin Very Small-Outline (DGV), Thin Shrink Small-Outline (PW), and Ceramic Flat (W) Packages, Ceramic Chip Carriers (FK), and Standard Plastic (N) and Ceramic (J) DIPs**

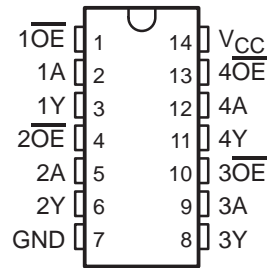
description

The 'AHCT125 devices are quadruple bus buffer gates featuring independent line drivers with 3-state outputs. Each output is disabled when the associated output-enable (\overline{OE}) input is high. When \overline{OE} is low, the respective gate passes the data from the A input to its Y output.

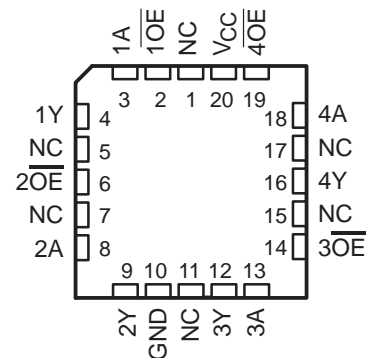
To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54AHCT125 is characterized for operation over the full military temperature range of -55°C to 125°C . The SN74AHCT125 is characterized for operation from -40°C to 85°C .

SN54AHCT125 . . . J OR W PACKAGE
SN74AHCT125 . . . D, DB, DGV, N, OR PW PACKAGE
(TOP VIEW)



SN54AHCT125 . . . FK PACKAGE
(TOP VIEW)



NC – No internal connection

FUNCTION TABLE
(each buffer)

INPUTS		OUTPUT
\overline{OE}	A	Y
L	H	H
L	L	L
H	X	Z



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 **TEXAS
INSTRUMENTS**

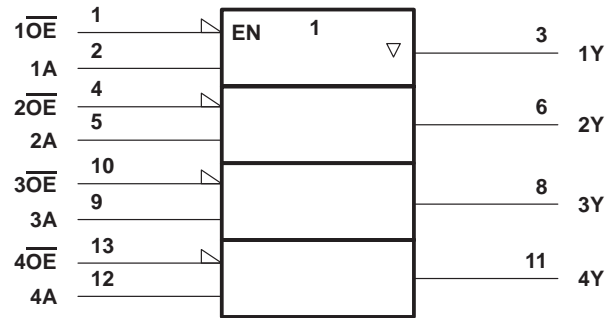
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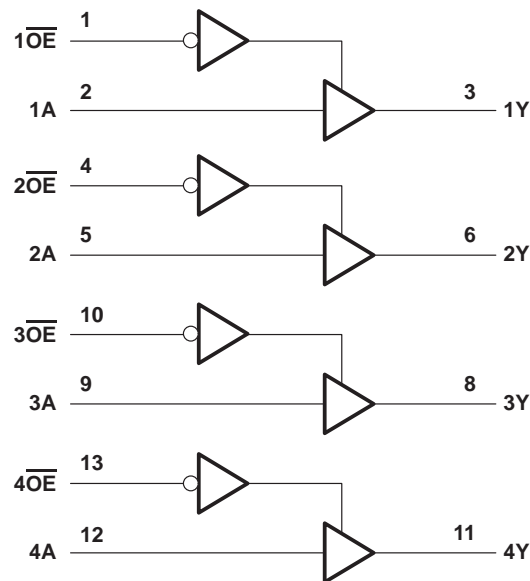
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logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the D, DB, DGV, J, N, PW, and W packages.

logic diagram (positive logic)



Pin numbers shown are for the D, DB, DGV, J, N, PW, and W packages.

SN54AHCT125, SN74AHCT125 QUADRUPLE BUS BUFFER GATES WITH 3-STATE OUTPUTS

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC}	–0.5 V to 7 V
Input voltage range, V_I (see Note 1)	–0.5 V to 7 V
Output voltage range, V_O (see Note 1)	–0.5 V to $V_{CC} + 0.5$ V
Input clamp current, I_{IK} ($V_I < 0$)	–20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$)	±20 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	±25 mA
Continuous current through V_{CC} or GND	±50 mA
Package thermal impedance, θ_{JA} (see Note 2): D package	86°C/W
DB package	96°C/W
DGV package	127°C/W
N package	80°C/W
PW package	113°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
 2. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions (see Note 3)

	SN54AHCT125		SN74AHCT125		UNIT
	MIN	MAX	MIN	MAX	
V_{CC} Supply voltage	4.5	5.5	4.5	5.5	V
V_{IH} High-level input voltage	2		2		V
V_{IL} Low-level input voltage		0.8		0.8	V
V_I Input voltage	0	5.5	0	5.5	V
V_O Output voltage	0	V_{CC}	0	V_{CC}	V
I_{OH} High-level output current		–8		–8	mA
I_{OL} Low-level output current		8		8	mA
$\Delta t/\Delta v$ Input transition rise or fall rate		20		20	ns/V
T_A Operating free-air temperature	–55	125	–40	85	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.



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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{CC}	T _A = 25°C			SN54AHCT125		SN74AHCT125		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V _{OH}	I _{OH} = -50 μA	4.5 V	4.4	4.5		4.4		4.4	V	
	I _{OH} = -8 mA		3.94			3.8		3.8		
V _{OL}	I _{OL} = 50 μA	4.5 V			0.1			0.1	V	
	I _{OL} = 8 mA				0.36		0.44	0.44		
I _I	V _I = V _{CC} or GND	0 V to 5.5 V			±0.1		±1*	±1	μA	
I _{OZ}	V _O = V _{CC} or GND	5.5 V			±0.25		±2.5	±2.5	μA	
I _{CC}	V _I = V _{CC} or GND, I _O = 0	5.5 V			2		20	20	μA	
ΔI _{CC} †	One input at 3.4 V, Other inputs at V _{CC} or GND	5.5 V			1.35		1.5	1.5	mA	
C _i	V _I = V _{CC} or GND	5 V		4	10			10	pF	
C _o	V _O = V _{CC} or GND	5 V		15					pF	

* On products compliant to MIL-PRF-38535, this parameter is not production tested at V_{CC} = 0 V.

† This is the increase in supply current for each input at one of the specified TTL voltage levels rather than 0 V or V_{CC}.

switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	T _A = 25°C			SN54AHCT125		SN74AHCT125		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t _{PLH}	A	Y	C _L = 15 pF		3.8**	5.5**	1**	6.5**	1	6.5	ns
t _{PHL}				3.8**	5.5**	1**	6.5**	1	6.5		
t _{PZH}	OE	Y	C _L = 15 pF		3.6**	5.1**	1**	6**	1	6	ns
t _{PZL}				3.6**	5.1**	1**	6**	1	6		
t _{PHZ}	OE	Y	C _L = 15 pF		4.6**	6.8**	1**	8**	1	8	ns
t _{PLZ}				4.6**	6.8**	1**	8**	1	8		
t _{PLH}	A	Y	C _L = 50 pF		5.3	7.5	1	8.5	1	8.5	ns
t _{PHL}				5.3	7.5	1	8.5	1	8.5		
t _{PZH}	OE	Y	C _L = 50 pF		5.1	7.1	1	8	1	8	ns
t _{PZL}				5.1	7.1	1	8	1	8		
t _{PHZ}	OE	Y	C _L = 50 pF		6.1	8.8	1	10	1	10	ns
t _{PLZ}				6.1	8.8	1	10	1	10		
t _{sk(o)}			C _L = 50 pF			1***			1	ns	

** On products compliant to MIL-PRF-38535, this parameter is not production tested.

*** On products compliant to MIL-PRF-38535, this parameter does not apply.

noise characteristics, V_{CC} = 5 V, C_L = 50 pF, T_A = 25°C (see Note 4)

PARAMETER	SN74AHCT125		UNIT
	MIN	MAX	
V _{OL(P)} Quiet output, maximum dynamic V _{OL}		0.8	V
V _{OL(V)} Quiet output, minimum dynamic V _{OL}		-0.8	V
V _{OH(V)} Quiet output, minimum dynamic V _{OH}	4.4		V
V _{IH(D)} High-level dynamic input voltage	2		V
V _{IL(D)} Low-level dynamic input voltage		0.8	V

NOTE 4: Characteristics are for surface-mount packages only.

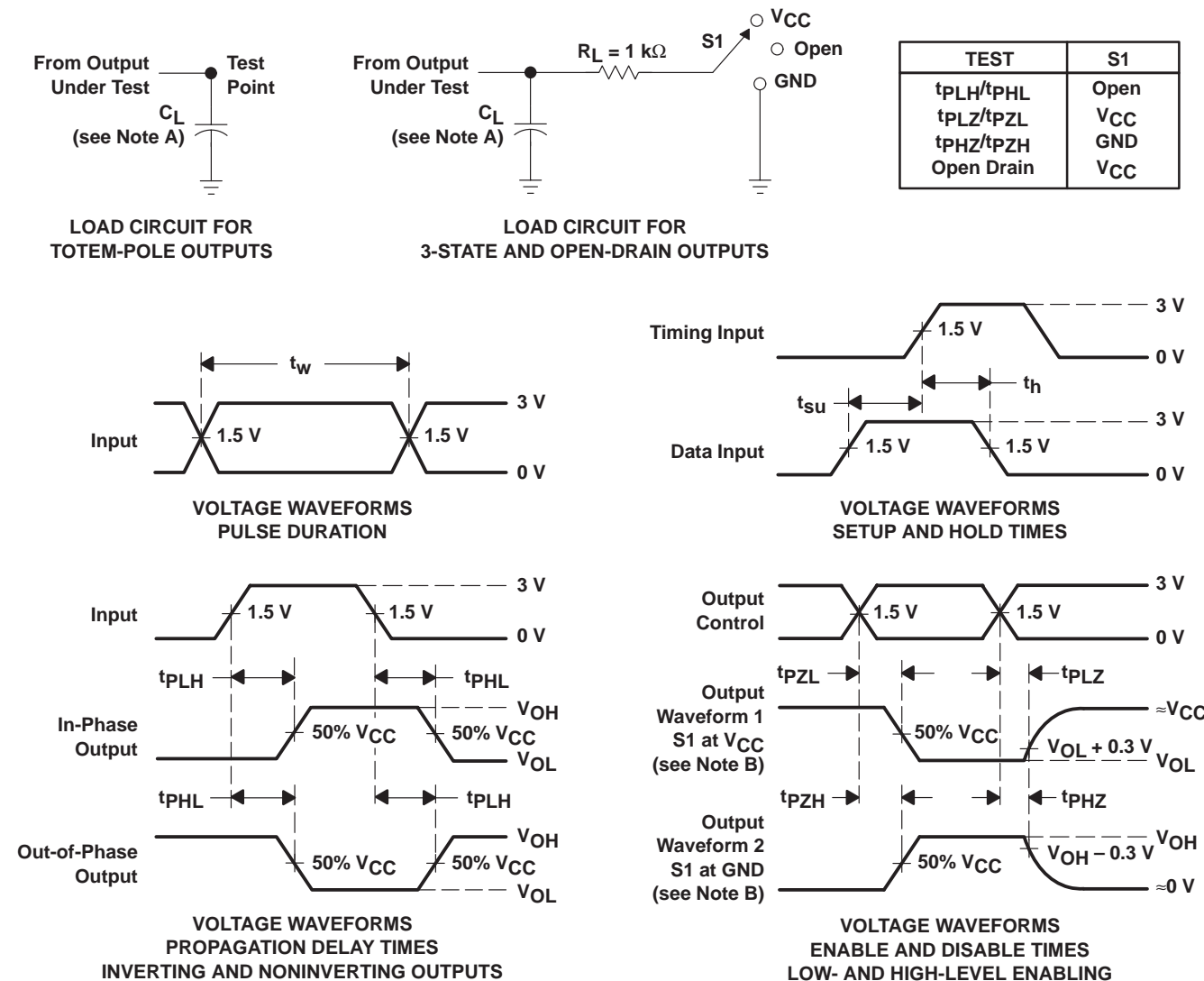


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operating characteristics, $V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$

PARAMETER	TEST CONDITIONS	TYP	UNIT
C_{pd} Power dissipation capacitance	No load, $f = 1\text{ MHz}$	14	pF

PARAMETER MEASUREMENT INFORMATION



- NOTES: A. C_L includes probe and jig capacitance.
 B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 1\text{ MHz}$, $Z_O = 50\ \Omega$, $t_r \leq 3\text{ ns}$, $t_f \leq 3\text{ ns}$.
 D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

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